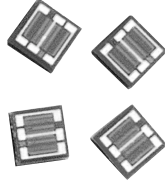


Dual Value, Chip Resistor Center Tap



Actual Size

These tantalum chips combine excellent stability with great power handling capacity. Two bonding pads per termination allow greater flexibility in hybrid layout design.

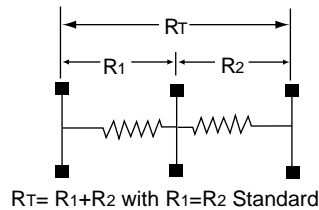
FEATURES

- Center tap feature
- Resistor material: self - passivating Tantalum Nitride
- Silicon substrate for good power dissipation
- Low cost

TYPICAL PERFORMANCE

	ABS	TRACKING
TCR	100	5
	ABS	RATIO
TOL	0.5	0.5

SCHEMATIC



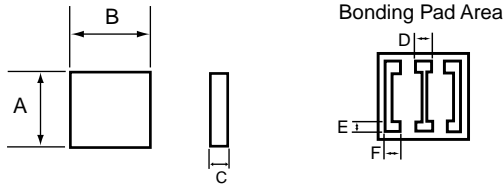
STANDARD ELECTRICAL SPECIFICATIONS

TEST	SPECIFICATIONS	CONDITIONS
MATERIAL	TANTALUM NITRIDE	
Resistance Range	50 ohms to 500Kohms	for $R_T = R_1 + R_2$
TCR:	Tracking	$\pm 5\text{ppm}/^\circ\text{C}$
	Absolute	$\pm 100\text{ppm}/^\circ\text{C}$ ($\pm 50\text{ppm}/^\circ\text{C}$ on Request)
Tolerance:	Ratio	1/1 standard
	Absolute	$\pm 0.5\%$, $\pm 1\%$, $\pm 2\%$
	Matching	$\pm 0.5\%$ Standard
Power Dissipation	250 mW at + 25°C, 125 mW at + 70°C, 50 mW at + 125°C	
Stability	$\pm 0.07\%$ typical, ± 0.1 Max.	2000 hrs. @ +70°C Under
Working Voltage	50 Volts DC on R_T	
Operating Temperature Range	-55°C to + 155°C	
Storage Temperature Range	-55°C to + 155°C	
Noise	<- 35 dB typical	MIL-STD-202 Method 308
Thermal EMF	0.01 $\mu\text{V}/^\circ\text{C}$	
Shelf Life Stability	100ppm	1 year @ +25°C

HYBRID



DIMENSIONS in inches and millimeters



DIMENSION	INCHES	MILLIMETERS
A	0.03 ± 0.004	0.76 ± 0.10
B	0.03 ± 0.004	0.76 ± 0.10
C	0.01 to 0.015	0.25 to 0.40
D	0.004	0.10
E	0.006	0.15
F	0.006	0.15

MECHANICAL SPECIFICATIONS	
Resistive Element	Tantalum Nitride
Substrate Material	Silicon
Passivation	Autopassivation
Bonding Pads	Aluminium

How to Order

Series	R _T Ohmic Value	Absolute Tolerance	Matching Tolerance
TA 33	100K $R_T = R_1 + R_2$	±0.5% ±0.5% ±1% ±2%	0.5%